NCP177

Linear Voltage Regulator - Fast Transient Response, Enable

500 mA

The NCP177 is CMOS LDO regulator featuring 500 mA output current. The input voltage is as low as 1.6 V and the output voltage can be set from 0.7 V.

Features

- Operating Input Voltage Range: 1.6 V to 5.5 V
- Output Voltage Range: 0.7 V to 3.6 V
- Quiescent Current typ. 60 μA
- Low Dropout: 200 mV Typ. at 500 mA, VOUT-NOM = 1.8 V
- High Output Voltage Accuracy ±0.8%
- Stable with Small 1 μF Ceramic Capacitors
- Over-current Protection
- Thermal Shutdown Protection: 175°C
- With (NCP177A) and Without (NCP177B) Output Discharge Function
- Available in XDFN4 1 mm x 1 mm x 0.4 mm Package
- This is a Pb-Free Device

Typical Applications

- Battery Powered Equipment
- Portable Communication Equipment
- Cameras, Image Sensors and Camcorders

Figure 1. Typical Application Schematic

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 10 of this data sheet.
**Figure 2. Internal Block Diagram**

**PIN FUNCTION DESCRIPTION**

<table>
<thead>
<tr>
<th>Pin No.</th>
<th>Pin Name</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>OUT</td>
<td>Regulated output voltage pin</td>
</tr>
<tr>
<td>2</td>
<td>GND</td>
<td>Power supply ground pin</td>
</tr>
<tr>
<td>3</td>
<td>EN</td>
<td>Enable pin (active &quot;H&quot;)</td>
</tr>
<tr>
<td>4</td>
<td>IN</td>
<td>Power supply input voltage pin</td>
</tr>
<tr>
<td></td>
<td>EPAD</td>
<td>Exposed pad should be tied to ground plane for better power dissipation</td>
</tr>
</tbody>
</table>

**ABSOLUTE MAXIMUM RATINGS**

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Voltage (Note 1)</td>
<td>IN</td>
<td>−0.3 to 6.0</td>
<td>V</td>
</tr>
<tr>
<td>Output Voltage</td>
<td>OUT</td>
<td>−0.3 to Vin + 0.3</td>
<td>V</td>
</tr>
<tr>
<td>Chip Enable Input</td>
<td>EN</td>
<td>−0.3 to 6.0</td>
<td>V</td>
</tr>
<tr>
<td>Output Current</td>
<td>I\text{OUT}</td>
<td>Internally Limited</td>
<td>mA</td>
</tr>
<tr>
<td>Maximum Junction Temperature</td>
<td>T\text{J(MAX)}</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>T\text{STG}</td>
<td>−55 to 150</td>
<td>°C</td>
</tr>
<tr>
<td>ESD Capability, Human Body Model (Note 2)</td>
<td>ESD\text{HBM}</td>
<td>2000</td>
<td>V</td>
</tr>
<tr>
<td>ESD Capability, Machine Model (Note 2)</td>
<td>ESD\text{MM}</td>
<td>200</td>
<td>V</td>
</tr>
</tbody>
</table>

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
2. This device series incorporates ESD protection and is tested by the following methods:
   - ESD Human Body Model tested per JESD22–A114
   - ESD Machine Model tested per JESD22–A115
   - Latchup Current Maximum Rating tested per JEDEC standard: JESD78

**THERMAL CHARACTERISTICS**

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Thermal Characteristics, XDFN4 (Note 3)</td>
<td>R\text{\mu A}</td>
<td>223</td>
<td>°C/W</td>
</tr>
</tbody>
</table>

3. Measured according to JEDEC board specification. Detailed description of the board can be found in JESD51–7
### ELECTRICAL CHARACTERISTICS

\( V_{IN} = V_{OUT-NOM} + 0.5 \text{ V or } V_{IN} = 1.6 \text{ V (whichever is higher), } V_{EN} = 1.2 \text{ V, } I_{OUT} = 1 \text{ mA, } C_{IN} = C_{OUT} = 1.0 \mu F, \ T_J = 25^\circ C \)

The specifications in bold are guaranteed at \(-40^\circ C \leq T_J \leq 85^\circ C\). (Note 4)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Test Conditions</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Voltage</td>
<td>( V_{OUT-NOM} \geq 1.8 \text{ V} ) ( T_J = +25^\circ C )</td>
<td>( V_{IN} )</td>
<td>1.6</td>
<td>5.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Output Voltage</td>
<td>( V_{OUT-NOM} \geq 1.8 \text{ V} ) ( T_J = +25^\circ C ) (-40^\circ C \leq T_J \leq 85^\circ C )</td>
<td>( V_{OUT} )</td>
<td>-0.8</td>
<td>0.8</td>
<td>%</td>
<td></td>
</tr>
<tr>
<td>Line Regulation</td>
<td>( V_{IN} = V_{OUT-NOM} + 0.5 \text{ V to 5.25 V} ) ( V_{IN} \geq 1.6 \text{ V} )</td>
<td>( \text{LineReg} )</td>
<td>0.02</td>
<td>0.1</td>
<td>%/V</td>
<td></td>
</tr>
<tr>
<td>Load Regulation</td>
<td>( 1 \text{ mA} \leq I_{OUT} \leq 500 \text{ mA}, V_{IN} \geq 1.75 \text{ V} )</td>
<td>( \text{LoadReg} )</td>
<td>1</td>
<td>10</td>
<td>mV</td>
<td></td>
</tr>
<tr>
<td>Dropout Voltage (Note 5)</td>
<td>( I_{OUT} = 500 \text{ mA} ) ( 1.4 \text{ V} \leq V_{OUT} &lt; 1.8 \text{ V} )</td>
<td>( V_{DO} )</td>
<td>140</td>
<td>180</td>
<td>mV</td>
<td></td>
</tr>
<tr>
<td>QUIESCENT CURRENT</td>
<td>( I_{OUT} = 0 \text{ mA} )</td>
<td>( I_Q )</td>
<td>60</td>
<td>90</td>
<td>( \mu A )</td>
<td></td>
</tr>
<tr>
<td>Standby Current</td>
<td>( V_{EN} = 0 \text{ V} )</td>
<td>( I_{STBY} )</td>
<td>0.1</td>
<td>1</td>
<td>( \mu A )</td>
<td></td>
</tr>
<tr>
<td>Output Current Limit</td>
<td>( V_{OUT} = V_{OUT-NOM} - 100 \text{ mV, } V_{IN} \geq 1.75 \text{ V} )</td>
<td>( I_{OUT} )</td>
<td>510</td>
<td>800</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Short Circuit Current</td>
<td>( V_{OUT} = 0 \text{ V}, V_{IN} \geq 1.75 \text{ V} )</td>
<td>( I_{SC} )</td>
<td>510</td>
<td>800</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>EN Pin Threshold Voltage</td>
<td>( EN \text{ Input Voltage &quot;H&quot;} )</td>
<td>( V_{ENH} )</td>
<td>1.0</td>
<td></td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Enable Input Current</td>
<td>( V_{EN} = V_{IN} = 5.5 \text{ V} )</td>
<td>( I_{EN} )</td>
<td>0.15</td>
<td>0.6</td>
<td>( \mu A )</td>
<td></td>
</tr>
<tr>
<td>Power Supply Rejection Ratio</td>
<td>( f = 1 \text{ kHz, Ripple 0.2 \text{ Vp-p,}} ) ( V_{IN} = V_{OUT-NOM} + 1.0 \text{ V, } I_{OUT} = 30 \text{ mA} ) ( V_{OUT} \leq 2.0 \text{ V, } V_{IN} = 3.0 \text{ V} )</td>
<td>( \text{PSRR} )</td>
<td>75</td>
<td></td>
<td>dB</td>
<td></td>
</tr>
<tr>
<td>Output Noise</td>
<td>( f = 10 \text{ Hz to 100 kHz} )</td>
<td></td>
<td>54</td>
<td></td>
<td>( \mu V_{RMS} )</td>
<td></td>
</tr>
<tr>
<td>Output Discharge Resistance (NCP177A option only)</td>
<td>( V_{IN} = 4.0 \text{ V, } V_{EN} = 0 \text{ V, } V_{OUT} = V_{OUT-NOM} )</td>
<td>( R_{ACTDIS} )</td>
<td>60</td>
<td></td>
<td>( \Omega )</td>
<td></td>
</tr>
<tr>
<td>Thermal Shutdown Temperature</td>
<td>Temperature rising from 25°C</td>
<td>( T_{SD_TEMP} )</td>
<td>175</td>
<td></td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>Thermal Shutdown Hysteresis</td>
<td>Temperature falling from ( T_{SD_TEMP} )</td>
<td>( T_{SD_HYST} )</td>
<td>20</td>
<td></td>
<td>°C</td>
<td></td>
</tr>
</tbody>
</table>

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Performance guaranteed over the indicated operating temperature range by design and/or characterization. Production tested at \( T_A = 25^\circ C \).

5. Low duty cycle pulse techniques are used during the testing to maintain the junction temperature as close to ambient as possible.

5. Measured when the output voltage falls 3% below the nominal output voltage (the voltage measured under the condition \( V_{IN} = V_{OUT-NOM} + 0.5 \text{ V} \)).
TYPICAL CHARACTERISTICS

\[ V_{\text{IN}} = V_{\text{OUT-NOM}} + 0.5 \text{ V or } V_{\text{IN}} = 1.6 \text{ V (whichever is higher)}, \quad V_{\text{EN}} = 1.2 \text{ V}, \quad I_{\text{OUT}} = 1 \text{ mA}, \quad C_{\text{IN}} = C_{\text{OUT}} = 1.0 \mu \text{F}, \quad T_{\text{J}} = 25^\circ \text{C} \]

**Figure 3. Output Voltage vs. Temperature**

**Figure 4. Output Voltage vs. Temperature**

**Figure 5. Output Voltage vs. Temperature**

**Figure 6. Line Regulation vs. Temperature**

**Figure 7. Load Regulation vs. Temperature**

**Figure 8. Dropout Voltage vs. Output Current**

\[ V_{\text{OUT-NOM}} = 0.7 \text{ V} \]

\[ V_{\text{OUT-NOM}} = 1.8 \text{ V} \]

\[ V_{\text{OUT-NOM}} = 3.3 \text{ V} \]
NCP177

TYPICAL CHARACTERISTICS

\[ V_{IN} = V_{OUT-NOM} + 0.5 \text{ V} \text{ or } V_{IN} = 1.6 \text{ V} \text{ (whichever is higher)}, \quad V_{EN} = 1.2 \text{ V}, \quad I_{OUT} = 1 \text{ mA}, \quad C_{IN} = C_{OUT} = 1.0 \mu F, \quad T_{J} = 25^\circ C \]

---

Figure 9. Dropout Voltage vs. Temperature

Figure 10. Dropout Voltage vs. Output Current

Figure 11. Dropout Voltage vs. Temperature

Figure 12. Standby Current vs. Temperature

Figure 13. Quiescent Current vs. Temperature

Figure 14. Quiescent Current vs. Input Voltage

---

www.onsemi.com
NCP177

TYPICAL CHARACTERISTICS

$V_{IN} = V_{OUT-NOM} + 0.5 \text{ V or } V_{IN} = 1.6 \text{ V (whichever is higher)}, V_{EN} = 1.2 \text{ V, } I_{OUT} = 1 \text{ mA, } C_{IN} = C_{OUT} = 1.0 \mu\text{F, } T_J = 25^{\circ}\text{C}$

Figure 15. Ground Current vs. Output Current

Figure 16. Short Circuit Current vs. Temperature

Figure 17. Output Current Limit vs. Temperature

Figure 18. Enable Threshold Voltage vs. Temperature

Figure 19. Enable Input Current vs. Temperature

Figure 20. Output Discharge Resistance vs. Temperature (NCP177A option only)
TYPICAL CHARACTERISTICS

\[ V_{IN} = V_{OUT-NOM} + 0.5 \, V \text{ or } V_{IN} = 1.6 \, V \text{ (whichever is higher)}, \ V_{EN} = 1.2 \, V, \ I_{OUT} = 1 \, mA, \ C_{IN} = C_{OUT} = 1.0 \, \mu F, \ T_{J} = 25^\circ C \]

Figure 21. Power Supply Rejection Ratio

Figure 22. Output Voltage Noise Spectral Density

Figure 23. Turn–ON/OFF – VIN Driven (slow)

Figure 24. Turn–ON – VIN Driven (fast)

Figure 25. Turn–ON/OFF – EN Driven

Figure 26. Line Transient Response
TYPICAL CHARACTERISTICS

V_IN = V_OUT - NOM + 0.5 V or V_IN = 1.6 V (whichever is higher), V_EN = 1.2 V, I_OUT = 1 mA, C_IN = C_OUT = 1.0 μF, T_J = 25°C

Figure 27. Load Transient Response

Figure 28. θ_{JA} and P_{D(MAX)} vs. Copper Area

APPLICATIONS INFORMATION

General

The NCP177 is a high performance 500 mA low dropout linear regulator (LDO) delivering excellent noise and dynamic performance. Thanks to its adaptive ground current behavior the device consumes only 60 μA of quiescent current (no-load condition).

The regulator features low noise of 48 μVRMS, PSRR of 75 dB at 1 kHz and very good line/load transient performance. Such excellent dynamic parameters, small dropout voltage and small package size make the device an ideal choice for powering the precision noise sensitive circuitry in portable applications.

A logic EN input provides ON/OFF control of the output voltage. When the EN is low the device consumes as low as 100 nA typ. from the IN pin.

The device is fully protected in case of output overload, output short circuit condition or overheating, assuring a very robust design.

Input Capacitor Selection (C_IN)

Input capacitor connected as close as possible is necessary to ensure device stability. The X7R or X5R capacitor should be used for reliable performance over temperature range. The value of the input capacitor should be 1 μF or greater for the best dynamic performance. This capacitor will provide a low impedance path for unwanted AC signals or noise modulated onto the input voltage.

There is no requirement for the ESR of the input capacitor but it is recommended to use ceramic capacitor for its low ESR and ESL. A good input capacitor will limit the influence of input trace inductance and source resistance during load current changes.

Output Capacitor Selection (C_OUT)

The LDO requires an output capacitor connected as close as possible to the output and ground pins. The recommended capacitor value is 1 μF, ceramic X7R or X5R type due to its low capacitance variations over the specified temperature range. The LDO is designed to remain stable with minimum effective capacitance of 0.8 μF. When selecting the capacitor the changes with temperature, DC bias and package size needs to be taken into account. Especially for small package size capacitors such as 0201 the effective capacitance drops rapidly with the applied DC bias voltage (refer the capacitor’s datasheet for details).

There is no requirement for the minimum value of equivalent series resistance (ESR) for the C_OUT but the maximum value of ESR should be less than 0.5 Ω. Larger capacitance and lower ESR improves the load transient response and high frequency PSRR. Only ceramic capacitors are recommended, the other types like tantalum capacitors not due to their large ESR.

Enable Operation

The LDO uses the EN pin to enable/disable its operation and to deactivate/activate the output discharge function (A-version only).

If the EN pin voltage is < 0.4 V the device is disabled and the pass transistor is turned off so there is no current flow between the IN and OUT pins. On A-version the active discharge transistor is active so the output voltage is pulled to GND through 60 Ω (typ.) resistor.

If the EN pin voltage is > 1.0 V the device is enabled and regulates the output voltage. The active discharge transistor is turned off.
The EN pin has internal pull-down current source with value of 300 nA typ. which assures the device is turned off when the EN pin is unconnected. In case when the EN function isn’t required the EN pin should be tied directly to IN pin.

**Output Current Limit**

Output current is internally limited to a 750 mA typ. The LDO will source this current when the output voltage drops down from the nominal output voltage (test condition is $V_{\text{OUT-NOM}} - 100 \text{ mV}$). If the output voltage is shorted to ground, the short circuit protection will limit the output current to 700 mA typ. The current limit and short circuit protection will work properly over the whole temperature and input voltage ranges. There is no limitation for the short circuit duration.

**Thermal Shutdown**

When the LDO’s die temperature exceeds the thermal shutdown threshold value the device is internally disabled. The IC will remain in this state until the die temperature decreases by value called thermal shutdown hysteresis. Once the IC temperature falls this way the LDO is back enabled. The thermal shutdown feature provides the protection against overheating due to some application failure and it is not intended to be used as a normal working function.

**Power Dissipation**

Power dissipation caused by voltage drop across the LDO and by the output current flowing through the device needs to be dissipated out from the chip. The maximum power dissipation is dependent on the PCB layout, number of used Cu layers, Cu layers thickness and the ambient temperature. The maximum power dissipation can be computed by following equation:

$$P_{D(MAX)} = \frac{T_J - T_A}{\theta_{JA}} = \frac{125 - T_A}{\theta_{JA}} \ [\text{W}] \quad (eq. 1)$$

Where: $(T_J - T_A)$ is the temperature difference between the junction and ambient temperatures and $\theta_{JA}$ is the thermal resistance (dependent on the PCB as mentioned above).

For reliable operation junction temperature should be limited do +125°C.

The power dissipated by the LDO for given application conditions can be calculated by the next equation:

$$P_D = V_{\text{IN}} \cdot I_{\text{GND}} + (V_{\text{IN}} - V_{\text{OUT}}) \cdot I_{\text{OUT}} \ [\text{W}] \quad (eq. 2)$$

Where: $I_{\text{GND}}$ is the LDO’s ground current, dependent on the output load current.

Connecting the exposed pad and N/C pin to a large ground planes helps to dissipate the heat from the chip.

The relation of $\theta_{JA}$ and $P_{D(MAX)}$ to PCB copper area and Cu layer thickness could be seen on the Figure 26.

**Reverse Current**

The PMOS pass transistor has an inherent body diode which will be forward biased in the case when $V_{\text{OUT}} > V_{\text{IN}}$. Due to this fact in cases, where the extended reverse current condition can be anticipated the device may require additional external protection.

**Power Supply Rejection Ratio**

The LDO features very high power supply rejection ratio. The PSRR at higher frequencies (in the range above 100 kHz) can be tuned by the selection of $C_{\text{OUT}}$ capacitor and proper PCB layout. A simple LC filter could be added to the LDO’s IN pin for further PSRR improvement.

**Enable Turn–On Time**

The enable turn–on time is defined as the time from EN assertion to the point in which $V_{\text{OUT}}$ will reach 98% of its nominal value. This time is dependent on various application conditions such as $V_{\text{OUT-NOM}}$, $C_{\text{OUT}}$ and $T_A$.

**PCB Layout Recommendations**

To obtain good transient performance and good regulation characteristics place $C_{\text{IN}}$ and $C_{\text{OUT}}$ capacitors as close as possible to the device pins and make the PCB traces wide. In order to minimize the solution size, use 0402 or 0201 capacitors size with appropriate effective capacitance. Larger copper area connected to the pins will also improve the device thermal resistance. The actual power dissipation can be calculated from the equation above (Power Dissipation section). Exposed pad and N/C pin should be tied to the ground plane for good power dissipation.
## ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Voltage Option</th>
<th>Option</th>
<th>Marking</th>
<th>Package</th>
<th>Shipping†</th>
</tr>
</thead>
<tbody>
<tr>
<td>NCP177AMX070TCG</td>
<td>0.70 V</td>
<td></td>
<td>JA</td>
<td>XDFN-4 (Pb–Free)</td>
<td>3000 / Tape &amp; Reel</td>
</tr>
<tr>
<td>NCP177AMX090TCG</td>
<td>0.90 V</td>
<td></td>
<td>JM</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX100TCG</td>
<td>1.00 V</td>
<td></td>
<td>JC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX110TCG</td>
<td>1.10 V</td>
<td></td>
<td>JD</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX120TCG</td>
<td>1.20 V</td>
<td></td>
<td>JE</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX125TCG</td>
<td>1.25 V</td>
<td></td>
<td>JK</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX135TCG</td>
<td>1.35 V</td>
<td></td>
<td>JC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX150TCG</td>
<td>1.50 V</td>
<td></td>
<td>JD</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX180TCG</td>
<td>1.80 V</td>
<td></td>
<td>JH</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177AMX330TCG</td>
<td>3.30 V</td>
<td></td>
<td>JJ</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX070TCG</td>
<td>0.70 V</td>
<td>Without output discharge</td>
<td>HA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX100TCG</td>
<td>1.00 V</td>
<td>Without output discharge</td>
<td>HC</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX110TCG</td>
<td>1.10 V</td>
<td>Without output discharge</td>
<td>HD</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX120TCG</td>
<td>1.20 V</td>
<td>Without output discharge</td>
<td>HE</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX125TCG</td>
<td>1.25 V</td>
<td>Without output discharge</td>
<td>HL</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX135TCG</td>
<td>1.35 V</td>
<td>Without output discharge</td>
<td>HF</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX150TCG</td>
<td>1.50 V</td>
<td>Without output discharge</td>
<td>HG</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX180TCG</td>
<td>1.80 V</td>
<td>Without output discharge</td>
<td>HH</td>
<td></td>
<td></td>
</tr>
<tr>
<td>NCP177BMX330TCG</td>
<td>3.30 V</td>
<td>Without output discharge</td>
<td>HJ</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
PACKAGE DIMENSIONS

XDFN4 1.0x1.0, 0.65P
CASE 711AJ
ISSUE A

NOTES:


2. CONTROLLING DIMENSION: MILLIMETERS.

3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM THE TERMINAL TIPS.

4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIMENSIONS: MILLIMETERS

MOUNTING FOOTPRINT*

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.